



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Jing Cheng Lin, et al.	§	Docket No.:	24061.485
		§		(TSMC2002-0360)
Serial No.:	10/618,536	§		
		§	Examiner:	Thien F. Tran
Filing Date:	June 11, 2003	§		
		§	Art Unit:	2811
For:	Adhesion Copper and Etch Stop	§		
	Layer for Copper Alloy	§	Conf. No.:	5026
		§		

TRANSMITTAL

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified patent application.

1. Response to Restriction Requirement;
2. Petition for Extension of Time (1-month);
3. Check in the amount of \$110.00; and
4. Return Receipt Postcard

The Director is authorized to charge any deficiency fees or credit any overpayments to Deposit Account No. 08-1394 of Haynes and Boone, LLP.

Respectfully submitted,

David M. O'Dell  
Reg. No. 42,044

Date: 10-20-04

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Box: Amendments, Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below:

Bonnie Boyce  
Name

10-20-04  
Date